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(54) Title: SELF-ALIGNED WIDE BACKSIDE POWER RAIL CONTACTS TO MULTIPLE TRANSISTOR SOURCES

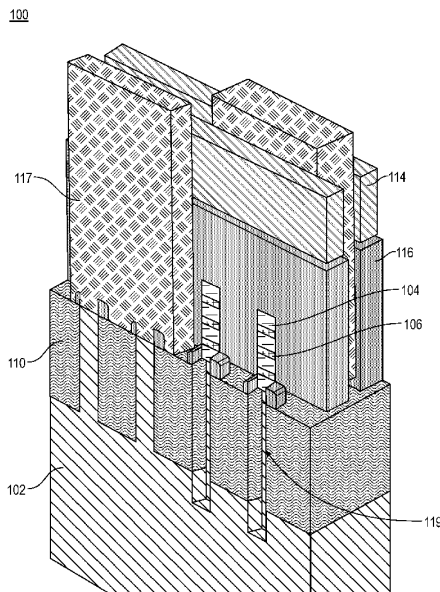


FIG. 2G

(57) Abstract: Semiconductor devices and methods of manufacturing the same are described. The method includes front side processing to form a deep source/drain cavity and filling the cavity with a sacrificial material. The sacrificial material is then removed during processing of the backside to form a backside power rail via that is filled with a metal fill.

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